

## General Description

The GreenMOS® high voltage MOSFET utilizes charge balance technology to achieve outstanding low on-resistance and lower gate charge. It is engineered to minimize conduction loss, provide superior switching performance and robust avalanche capability.

The GreenMOS® Generic series is optimized for extreme switching performance to minimize switching loss. It is tailored for high power density applications to meet the highest efficiency standards.

## Features

- Low  $R_{DS(on)}$  & FOM
- Extremely low switching loss
- Excellent stability and uniformity



## Applications

- PC power
- LED lighting
- Telecom power
- Server power
- EV Charger
- Solar/UPS

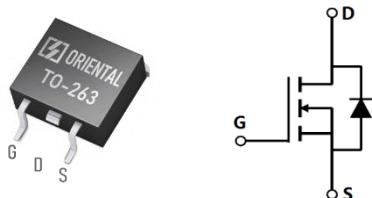
## Key Performance Parameters

Parameter	Value	Unit
$V_{DS, min} @ T_{j(max)}$	700	V
$I_D, pulse$	75	A
$R_{DS(ON), max} @ V_{GS}=10V$	125	mΩ
$Q_g$	41.9	nC

## Marking Information

Product Name	Package	Marking
OSG65R125KF	TO263	OSG65R125K

## Package & Pin Information



**Absolute Maximum Ratings** at  $T_j=25^\circ\text{C}$  unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-source voltage	$V_{DS}$	650	V
Gate-source voltage	$V_{GS}$	$\pm 30$	V
Continuous drain current <sup>1)</sup> , $T_C=25\text{ }^\circ\text{C}$	$I_D$	25	A
Continuous drain current <sup>1)</sup> , $T_C=100\text{ }^\circ\text{C}$		16	
Pulsed drain current <sup>2)</sup> , $T_C=25\text{ }^\circ\text{C}$	$I_{D,\text{pulse}}$	75	A
Continuous diode forward current <sup>1)</sup> , $T_C=25\text{ }^\circ\text{C}$	$I_S$	25	A
Diode pulsed current <sup>2)</sup> , $T_C=25\text{ }^\circ\text{C}$	$I_{S,\text{pulse}}$	75	A
Power dissipation <sup>3)</sup> , $T_C=25\text{ }^\circ\text{C}$	$P_D$	219	W
Single pulsed avalanche energy <sup>5)</sup>	$E_{AS}$	730	mJ
MOSFET dv/dt ruggedness, $V_{DS}=0\text{...}480\text{ V}$	dv/dt	50	V/ns
Reverse diode dv/dt, $V_{DS}=0\text{...}480\text{ V}$ , $I_{SD}\leq I_D$	dv/dt	15	V/ns
Operation and storage temperature	$T_{stg}, T_j$	-55 to 150	°C

**Thermal Characteristics**

Parameter	Symbol	Value	Unit
Thermal resistance, junction-case	$R_{\theta JC}$	0.57	°C/W
Thermal resistance, junction-ambient <sup>4)</sup>	$R_{\theta JA}$	62	°C/W

**Electrical Characteristics** at  $T_j=25^\circ\text{C}$  unless otherwise specified

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Drain-source breakdown voltage	$BV_{DSS}$	650			V	$V_{GS}=0\text{ V}$ , $I_D=1\text{ mA}$
		700	740			$V_{GS}=0\text{ V}$ , $I_D=1\text{ mA}$ , $T_j=150\text{ }^\circ\text{C}$
Gate threshold voltage	$V_{GS(\text{th})}$	2.9		3.9	V	$V_{DS}=V_{GS}$ , $I_D=1\text{ mA}$
Drain-source on-state resistance	$R_{DS(\text{ON})}$		0.115	0.125	$\Omega$	$V_{GS}=10\text{ V}$ , $I_D=12.5\text{ A}$
			0.278			$V_{GS}=10\text{ V}$ , $I_D=12.5\text{ A}$ , $T_j=150\text{ }^\circ\text{C}$
Gate-source leakage current	$I_{GSS}$			100	nA	$V_{GS}=30\text{ V}$
				-100		$V_{GS}=-30\text{ V}$
Drain-source leakage current	$I_{DSS}$			1	$\mu\text{A}$	$V_{DS}=650\text{ V}$ , $V_{GS}=0\text{ V}$

### Dynamic Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Input capacitance	C <sub>iss</sub>		2390.8		pF	V <sub>GS</sub> =0 V, V <sub>DS</sub> =50 V, f=100 kHz
Output capacitance	C <sub>oss</sub>		154.1		pF	
Reverse transfer capacitance	C <sub>rss</sub>		3.9		pF	
Turn-on delay time	t <sub>d(on)</sub>		32.4		ns	V <sub>GS</sub> =10 V, V <sub>DS</sub> =400 V, R <sub>G</sub> =2 Ω, I <sub>D</sub> =12.5 A
Rise time	t <sub>r</sub>		30.8		ns	
Turn-off delay time	t <sub>d(off)</sub>		63.2		ns	
Fall time	t <sub>f</sub>		4.9		ns	

### Gate Charge Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Total gate charge	Q <sub>g</sub>		41.9		nC	V <sub>GS</sub> =10 V, V <sub>DS</sub> =400 V, I <sub>D</sub> =12.5 A
Gate-source charge	Q <sub>gs</sub>		10.4		nC	
Gate-drain charge	Q <sub>gd</sub>		14.1		nC	
Gate plateau voltage	V <sub>plateau</sub>		5.7		V	

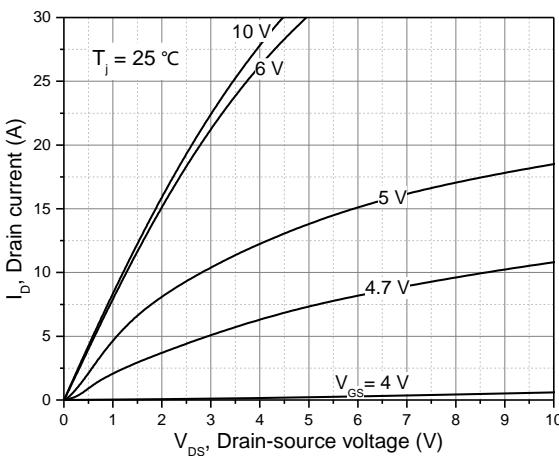
### Body Diode Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Diode forward voltage	V <sub>SD</sub>			1.4	V	I <sub>S</sub> =25 A, V <sub>GS</sub> =0 V
Reverse recovery time	t <sub>rr</sub>		365.2		ns	
Reverse recovery charge	Q <sub>rr</sub>		4.7		μC	
Peak reverse recovery current	I <sub>rrm</sub>		24.9		A	

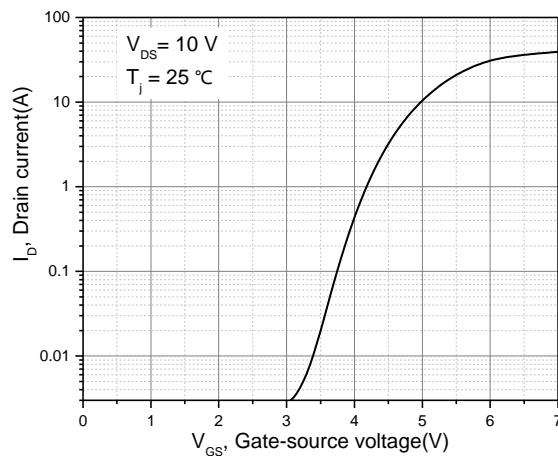
### Note

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3) Pd is based on max. junction temperature, using junction-case thermal resistance.
- 4) The value of R<sub>θJA</sub> is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with T<sub>a</sub>=25 °C.
- 5) V<sub>DD</sub>=100 V, V<sub>GS</sub>=10 V, L=80 mH, starting T<sub>j</sub>=25 °C.

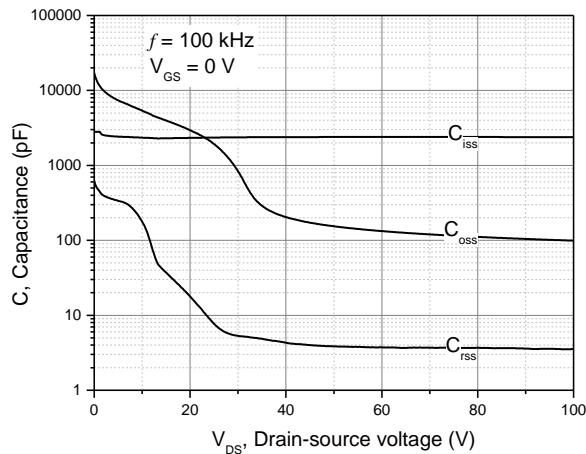
### Electrical Characteristics Diagrams



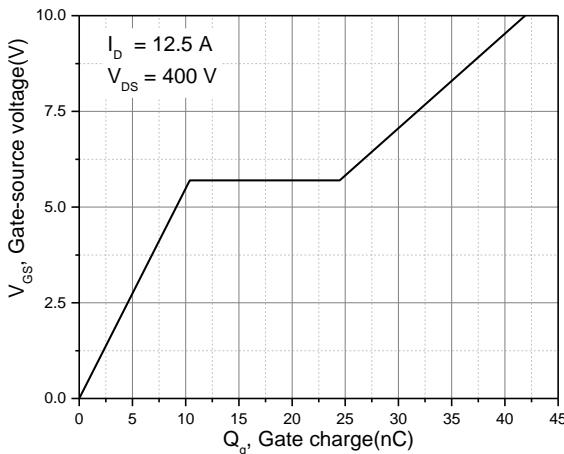
**Figure 1. Typ. output characteristics**



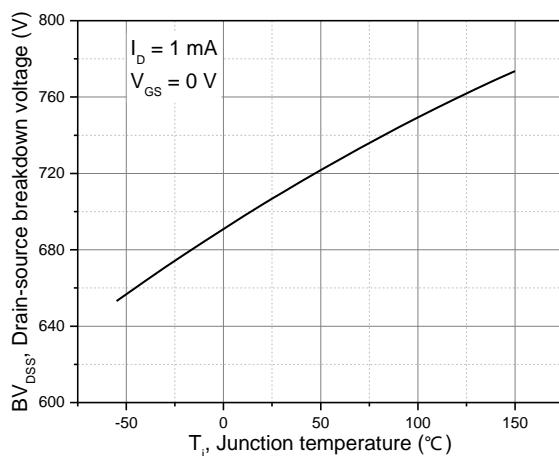
**Figure 2. Typ. transfer characteristics**



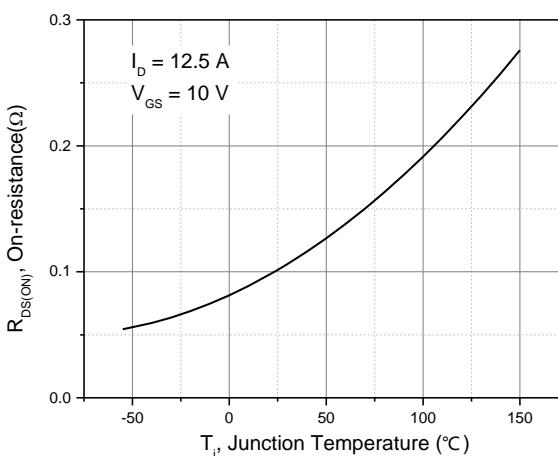
**Figure 3. Typ. capacitances**



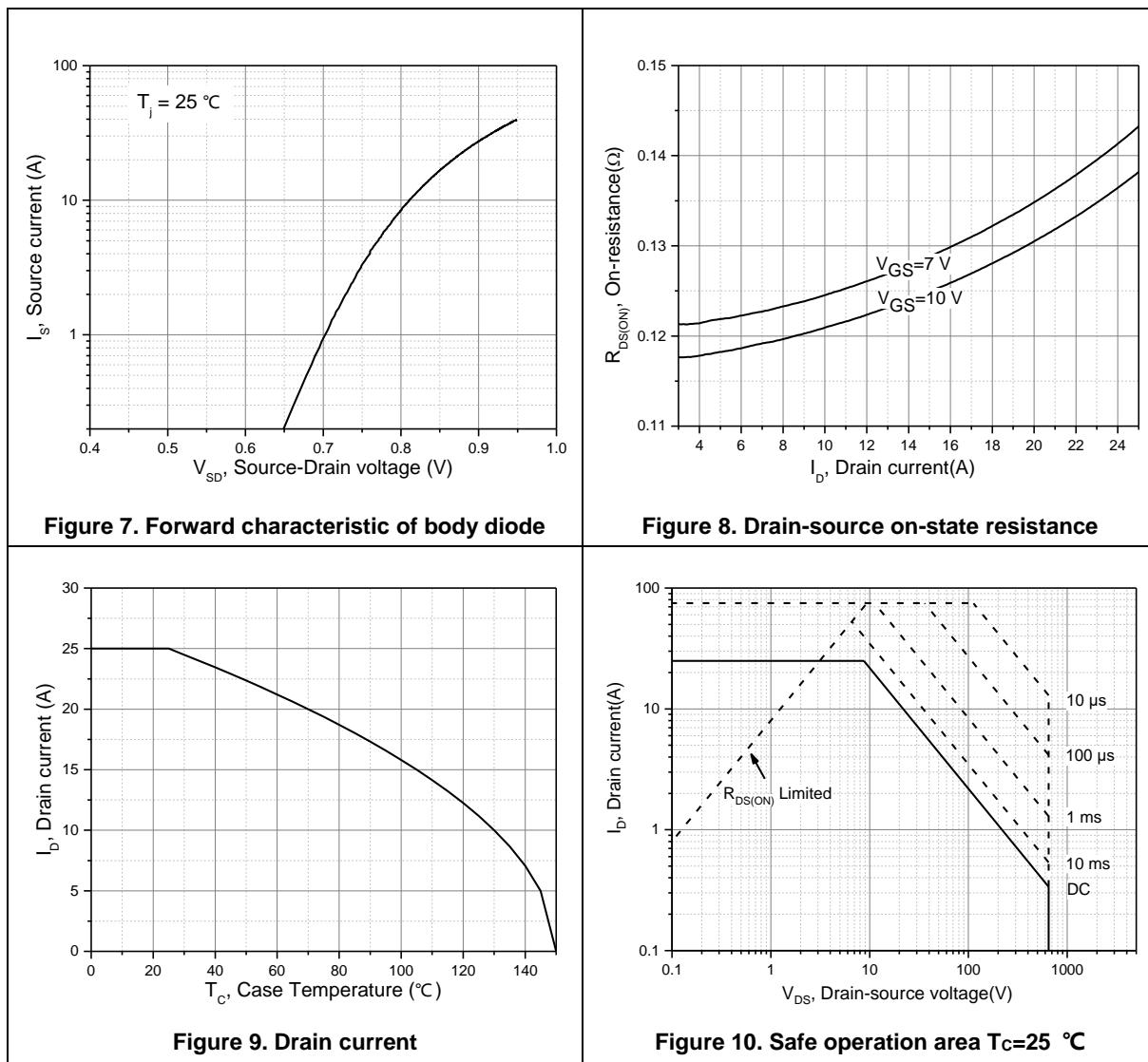
**Figure 4. Typ. gate charge**

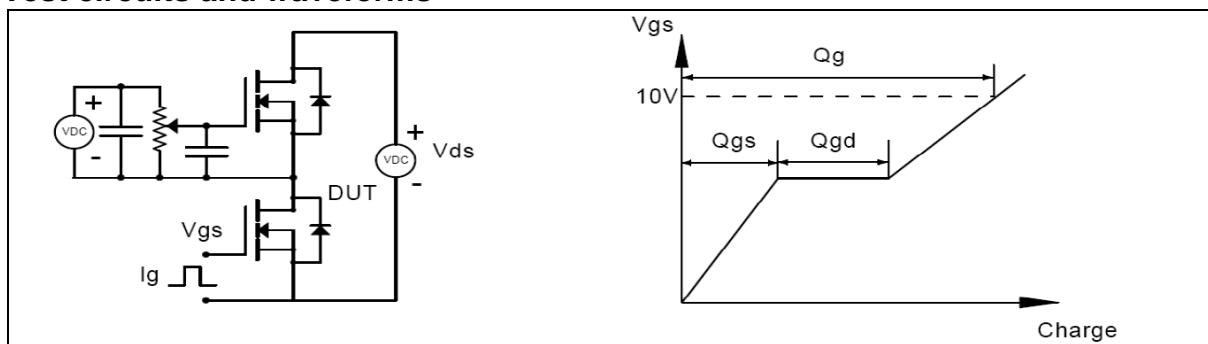
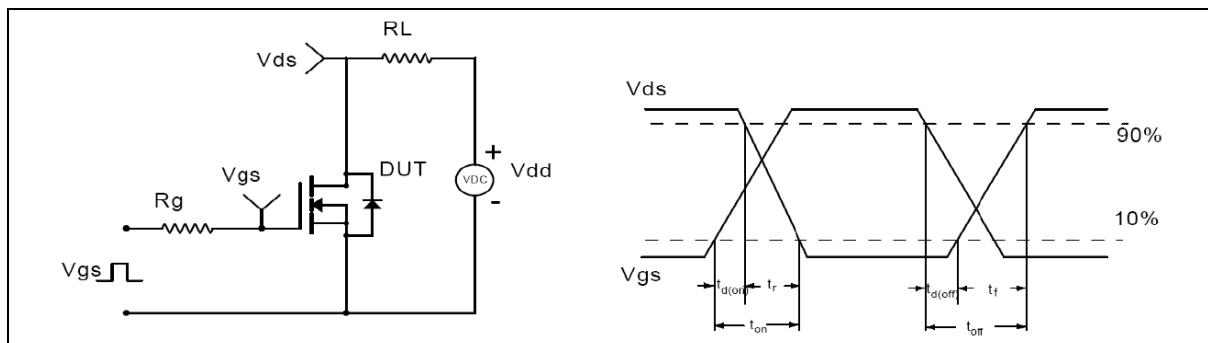
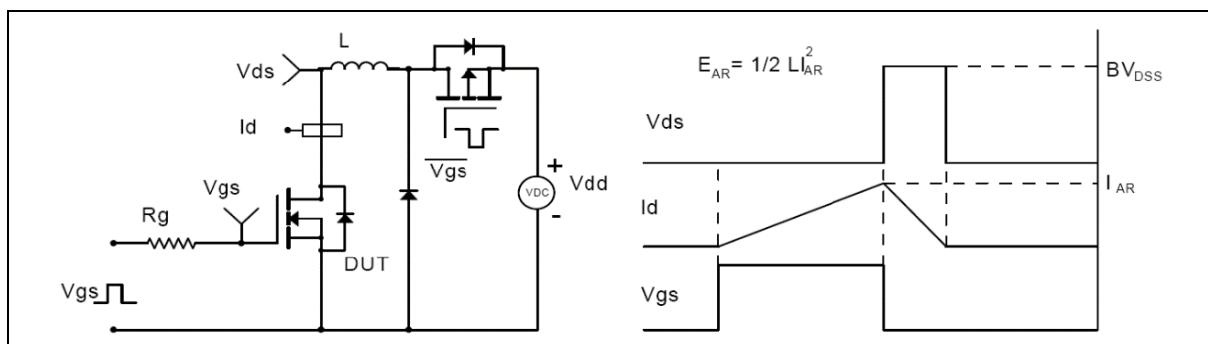
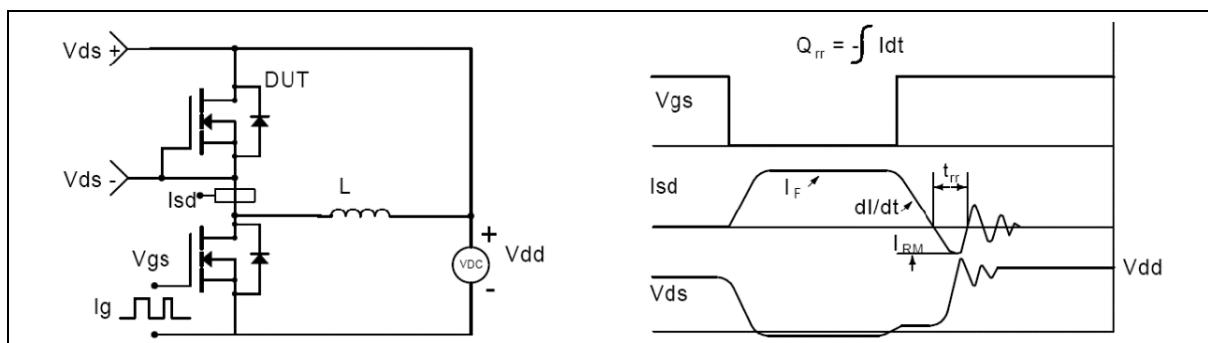


**Figure 5. Drain-source breakdown voltage**

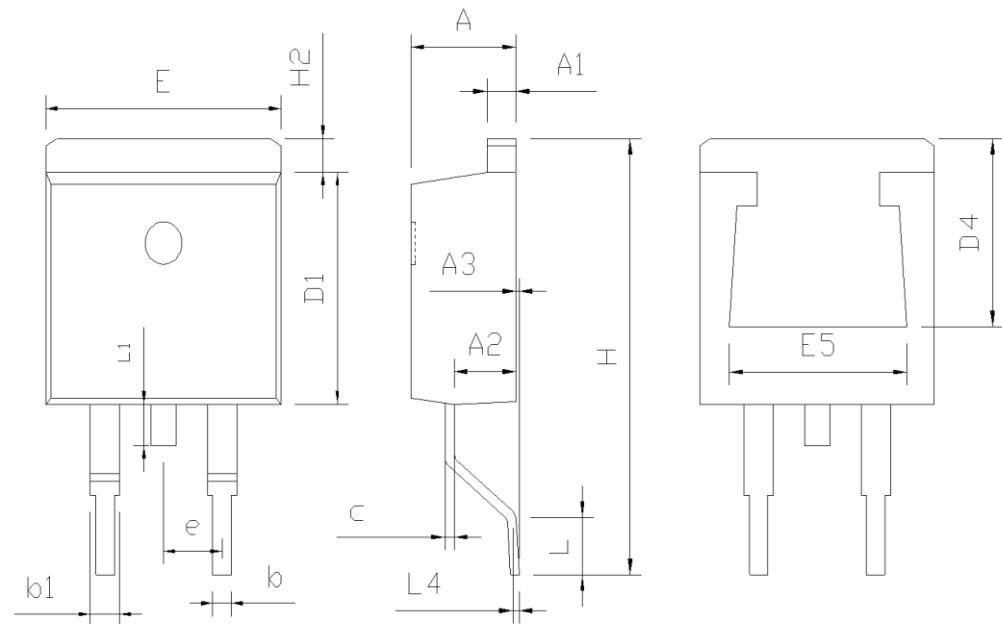


**Figure 6. Drain-source on-state resistance**



**Test circuits and waveforms**

**Figure 1. Gate charge test circuit & waveform**

**Figure 2. Switching time test circuit & waveforms**

**Figure 3. Unclamped inductive switching (UIS) test circuit & waveforms**

**Figure 4. Diode reverse recovery test circuit & waveforms**

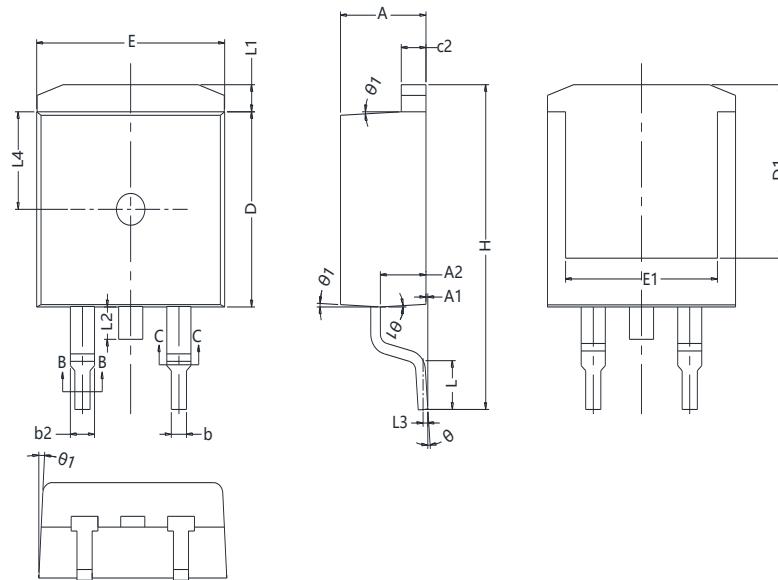
## Package Information



Symbol	mm		
	Min	Nom	Max
A	4.37	4.57	4.77
A1	1.22	1.27	1.42
A2	2.49	2.69	2.89
A3	0.00	0.13	0.25
b	0.70	0.81	0.96
b1	1.17	1.27	1.47
c	0.30	0.38	0.53
D1	8.50	8.70	8.90
D4	6.60	-	-
E	9.86	10.16	10.36
E5	7.06	-	-
e	2.54 BSC		
H	14.70	15.10	15.50
H2	1.07	1.27	1.47
L	2.00	2.30	2.60
L1	1.40	1.55	1.70
L4	0.25 BSC		
θ	0°	5°	9°

Version1: TO263-C package outline dimension

## Package Information



Symbol	mm		
	Min	Nom	Max
A	4.40	4.50	4.60
A1	0.00	0.10	0.25
A2	2.20	2.40	2.60
b	0.76	-	0.89
b1	0.75	0.80	0.85
b2	1.23	-	1.37
b3	1.22	1.27	1.32
c	0.47	-	0.60
c1	0.46	0.51	0.56
c2	1.25	1.30	1.35
D	9.10	9.20	9.30
D1	8.00	-	-
E	9.80	9.90	10.00
E1	7.80	-	-
e	2.54 BSC		
H	14.90	15.30	15.70
L	2.00	2.30	2.60
L1	1.17	1.27	1.40
L2	-	-	1.75
L3	0.25 BSC		
L4	4.60 REF		
θ	0°	-	8°
θ1	1°	3°	5°

Version2: TO263-J package outline dimension

## Ordering Information

Package Type	Units/Reel	Reels/Inner Box	Units/Inner Box	Inner Boxes/Carton Box	Units/Carton Box
TO263-C	800	1	800	5	4000
TO263-J	800	1	800	10	8000

## Product Information

Product	Package	Pb Free	RoHS	Halogen Free
OSG65R125KF	TO263	yes	yes	yes

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